

**In the Claims:**

Please amend claims 10, 11 and 14. Please add new claim 43. The claims are as follows:

1-9. (Canceled)

10. (Currently Amended) A method for dissipating heat from an electronic package having one or more components, comprising:

providing a substrate having a first coefficient of thermal expansion;

providing a lid, said lid having a top wall, a bottom wall and sidewalls connecting said top and bottom walls, said top, bottom and sidewalls defining a vapor chamber, said vapor chamber containing a heat transfer fluid, said lid having a second coefficient of thermal expansion said second coefficient of thermal expansion about equal to said first coefficient of thermal expansion;

providing a peripheral lid support, said peripheral lid support separate from said lid, said lid support having sidewalls defining a cavity open at top and bottom surfaces of said lid support;

attaching said top surface said peripheral lid support to a bottom surface of said sidewalls of said lid and attaching said bottom surface of said peripheral lid support to a periphery of said substrate, said bottom wall of said lid not attached to or touching said peripheral lid support;

providing a solid thermal transfer medium in direct contact with a back surface of each component and an outer surface of said bottom wall of said lid;

mounting each component directly to a top surface of said substrate; and

electrically connecting each component to said substrate.

11. (Currently Amended) The method of claim 10, wherein said upper wall and said sidewalls of said lid has have said second coefficient of thermal expansion, said bottom wall of said lid is separate from said upper wall and sidewalls of said lid, said bottom wall of said lid has a third coefficient of thermal expansion, each said component has a fourth coefficient of thermal expansion, said third coefficient of thermal expansion is about equal to said fourth coefficient of thermal expansion and said second coefficient of thermal expansion different from said third coefficient of thermal expansion.

12. (Previously Presented) The method of claim 10, further including:

mounting a heat sink having a third coefficient of thermal expansion to an outer surface of said top wall of said lid.

13. (Previously Presented) The method of claim 10, wherein said bottom wall of said lid has protruding first regions for maintaining equivalent contact with said thermal transfer medium on thin components of said one or more components as is maintained by second non-protruding regions on thick components of said one or more components, said first regions thicker than said second regions.

14. (Currently Amended) The method of claim 10, further including:

providing supports within said vapor chamber, each support having a vertical member extending between an upper said top wall of said vapor chamber lid and said bottom wall of said lid some or all of said supports, each vertical member perpendicular to said top and bottom walls and each vertical member aligned over some or all of said one or more of said components.

15. (Original) The method of claim 10, wherein said package is selected from the group consisting of ball grid array modules, pin grid array modules, land grid array modules and HyperBGA™ modules.

16. (Previously Presented) The method of claim 10, wherein said lid is formed from material selected from the group consisting of aluminum, copper, Invar, gold, silver, nickel, aluminum-silicon carbide, plastics, ceramics and composites.

17. (Original) The method of claim 10, wherein said substrate includes material selected from the group consisting of ceramics, fiberglass, polytetrafluoroethylene, and polymers.

18-20 (Canceled)

21. (Previously Presented) The method of claim 10, wherein said lower wall of said lid is formed from a different material than sidewalls and an upper wall of said lid.

22. (Previously Presented) The method of claim 10, wherein an upper wall of said lid has said second coefficient of thermal expansion, said lower wall of said lid has a third coefficient of thermal expansion.

23 -- 32 (Canceled)

33. (Previously Presented) The method of claim 12, wherein said third coefficient of thermal expansion is between about 25% and about 700% of said second coefficient of thermal expansion.

34. (Previously Presented) The method of claim 22, wherein each said component has a fourth coefficient of thermal expansion and said third coefficient of thermal expansion is between about 50% to about 700% of said fourth coefficient of thermal expansion.

35. (Previously Presented) The method of claim 10, wherein said first coefficient of thermal expansion is between about 25% to about 700% of said second coefficient of thermal expansion.

36. (Previously Presented) The method of claim 10, wherein said peripheral lid support is fabricated from the same material as said sidewalls of said lid.

37. (Previously Presented) The method of claim 10, wherein said bottom wall of said lid is fabricated from a different material than said sidewalls of said lid.

38. (Previously Presented) The method of claim of claim 14, wherein said supports are bars dividing said vapor chamber into sub-chambers.

39. (Previously Presented) The method of claim 38, wherein sides of said bars include through holes interconnecting said sub-chambers.

40. (Previously Presented) The method of claim 14, wherein said supports are vertical bars and do not extend beyond peripheries of said one or more components.

41. (Previously Presented) The method of claim 10, wherein said sidewalls of said lid comprise bellows.

42. (Previously Presented) The method of claim 41, further including providing supports within said vapor chamber, said supports comprising bellows, each bellows aligned over a corresponding component of said one or more components.

43. (New) The method of claim 10, wherein said substrate comprises polytetrafluoroethylene.